

Abstract of the Disclosure

The present invention allows non-wafer form devices to be tested on a standard automatic wafer-probe tester or other automated test or measurement device commonly employed in semiconductor or allied industries (e.g., flat panel display, data storage, or the like) processes. The present invention accomplishes this by providing a low-profile carrier for temporarily mounting a non-wafer form device. The low-profile carrier holds the non-wafer form device (e.g., an integrated circuit chip, a thin film head structure, one or more molded array packages, etc.) magnetically into recesses which are machined or otherwise formed in the low-profile carrier.